

SPECIFICATION FOR Near UV LED

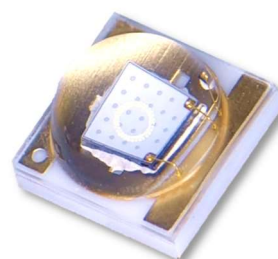
3535 UVA 395nm LED PKG

DESCRIPTION

The AO35LV395L01X is a UV LED package based on Al₂O₃ with a peak wavelength of 395 nm.

This product is generally used as indicator and luminary for electronic equipment.

And it This product is mainly used as industrial UV curing and general.



FEATURES

- Dimension (L x W x H) in mm
 - 3.45 x 3.45 x 2.2
- Forward current: up to 1,500 mA
- Radiant power (typ.)
 - 1,200 mW at 500 mA
- Viewing Angle ($2\theta_{1/2}$)
 - Typical 120°
- Built in ESD Protection device

APPLICATIONS

- UV Curing
- Moth killing
- Nail gel cure
- Counterfeit Detectors

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1. PKG Specifications

1) Absolute maximum ratings

[Ta=25°C]

| Parameters | Symbol | Value | Unit |
|-----------------------|--------|-------------|------|
| Forward current | If | 1,500 | mA |
| Power dissipation | Pd | 5.60 | W |
| Operating temperature | Topr | - 30 ~ +80 | °C |
| Storage temperature | Tstg | - 40 ~ +100 | °C |
| Junction Temperature | Tj | 125 | °C |
| Soldering temperature | Tsol | 260*) | °C |
| ESD Classification | | Class2**) | |

Notes

*) Recommend JEDEC-J-STD-020D for reflow soldering.

***) The ESD test follows JESD22-A114.

2) Electrical and Optical Characteristics

[Ta=25°C]

| Parameter | Symbol | If | Min | Typ | Max | Unit |
|----------------------------|-----------------|-------|-------|-------|-------|------|
| Peak wavelength | λ_p | 500mA | 390 | 395 | 400 | nm |
| Radiant Flux | Φ_e | 500mA | 1,010 | 1,200 | 1,450 | mW |
| Forward voltage | Vf | 500mA | 3.2 | 3.35 | 3.6 | V |
| Full Width at Half Maximum | $\Delta\lambda$ | 500mA | 11.0 | | | nm |
| Viewing angle | $2\theta_{1/2}$ | 500mA | 120 | | | deg |
| Thermal resistance | $R\theta_{J-S}$ | 500mA | 3.1 | | | °C/W |

Notes

- Peak Wavelength(λ_p) Measurement tolerance is ± 3 nm.
- Radiant Flux(Φ_e) Measurement tolerance is $\pm 10\%$.
- Forward Voltage(Vf) Measurement tolerance is $\pm 3\%$.
- Viewing angle(deg) Measurement tolerance is ± 5 deg.

2. Bin Structures

[If=500mA, Ta=25°C]

| Item | Bin | Min | Max | Unit |
|-----------------|-----|-------|-------|------|
| Peak Wavelength | W1 | 390 | 395 | nm |
| | W2 | 395 | 400 | |
| Radiant Flux | R1 | 1,010 | 1,120 | mW |
| | R2 | 1,120 | 1,230 | |
| | R3 | 1,230 | 1,340 | |
| | R4 | 1,340 | 1,450 | |
| Forward Voltage | V1 | 3.2 | 3.3 | V |
| | V2 | 3.3 | 3.4 | |
| | V3 | 3.4 | 3.5 | |
| | V4 | 3.5 | 3.6 | |

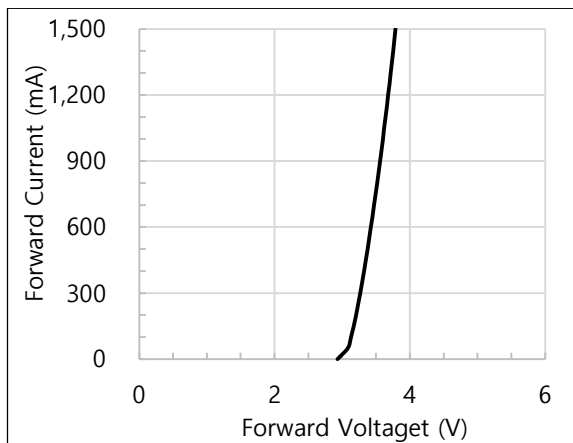
Notes

- Peak Wavelength(λ_p) Measurement tolerance is $\pm 3\text{nm}$.
- Radiant Flux(Φ_e) Measurement tolerance is $\pm 10\%$.
- Forward Voltage(V_f) Measurement tolerance is $\pm 3\%$.

3. Typical Characteristics Graphs

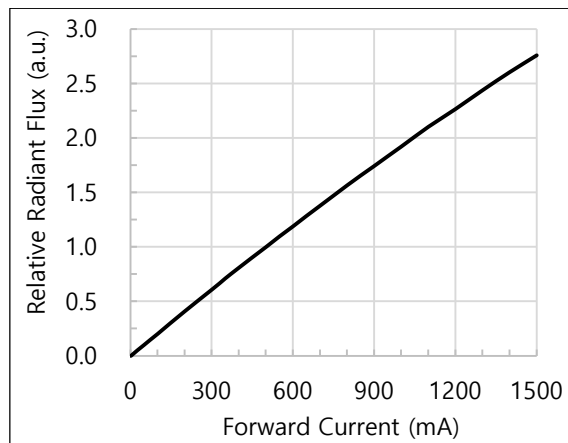
1) Forward Current vs. Forward Voltage

[Ta=25°C]



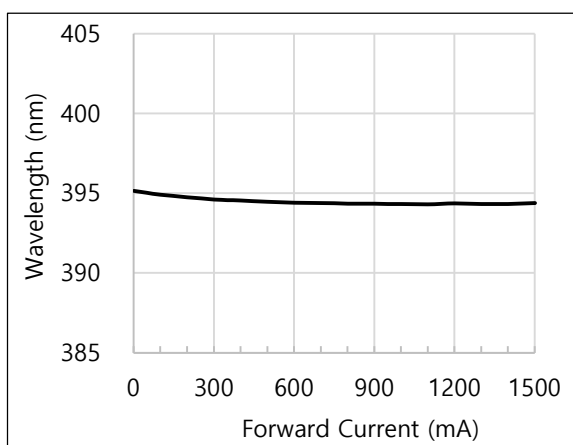
2) Relative Radiant Flux vs. Forward Current

[Ta=25°C]



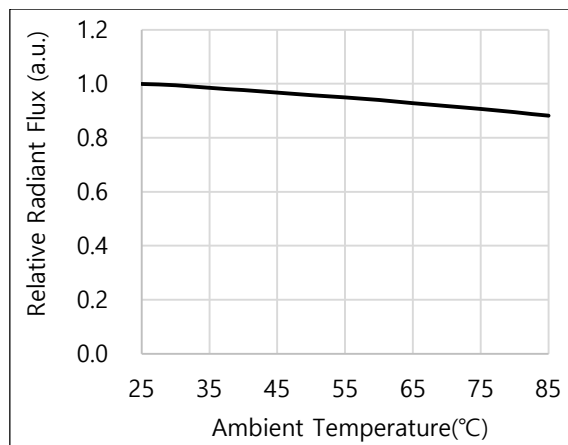
3) Peak Wavelength vs. Forward Current

[Ta=25°C]



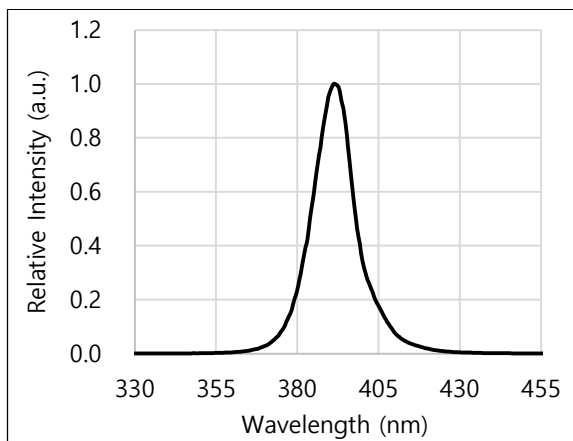
4) Ambient Temp. vs. Relative Radiant Flux

[Ta=25°C]



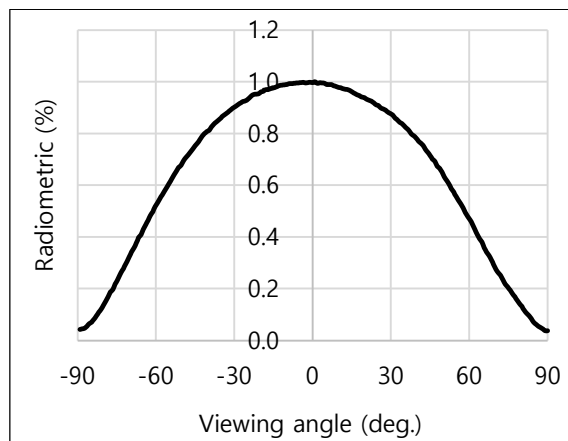
5) Spectrum

[Ta=25°C]



6) Typical Spatial Distribution

[Ta=25°C]

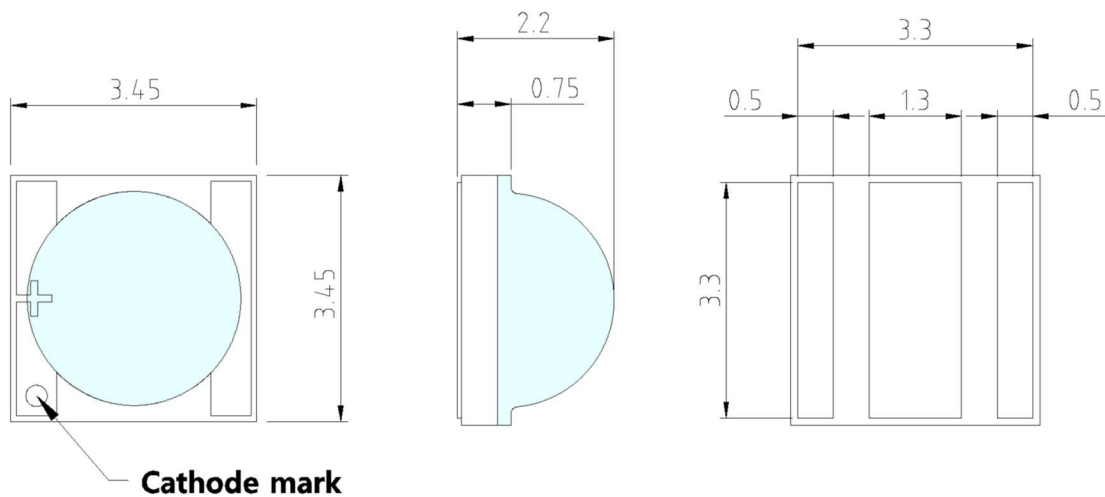


4. Outline Dimensions

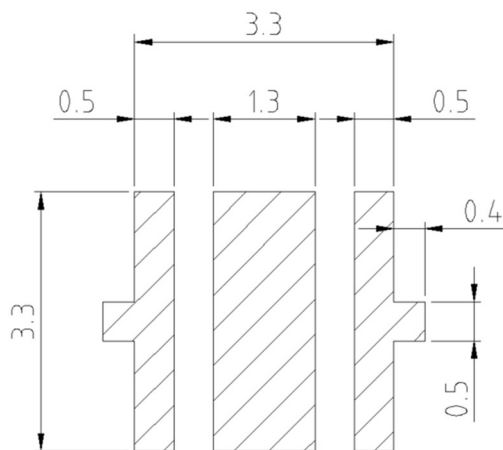
1) PKG Dimensions

- PKG Dimensions - 3.45 x 3.45 x 2.2(L x W x H)
- Undefined tolerance is $\pm 0.2\text{mm}$

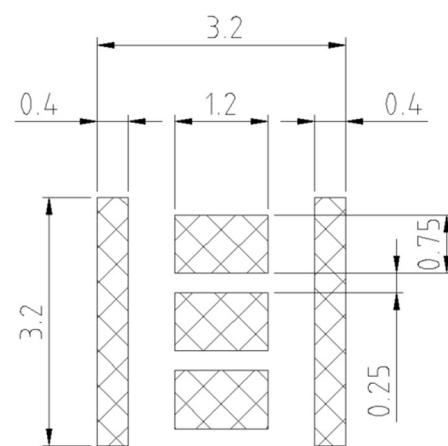
[Unit : mm]



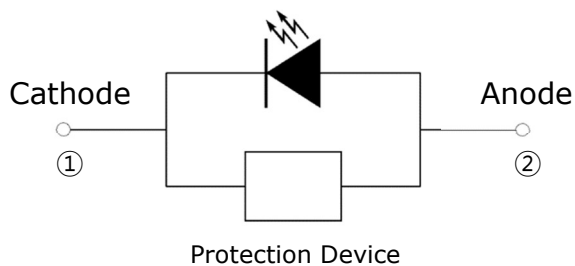
2) Recommended Solder Pad



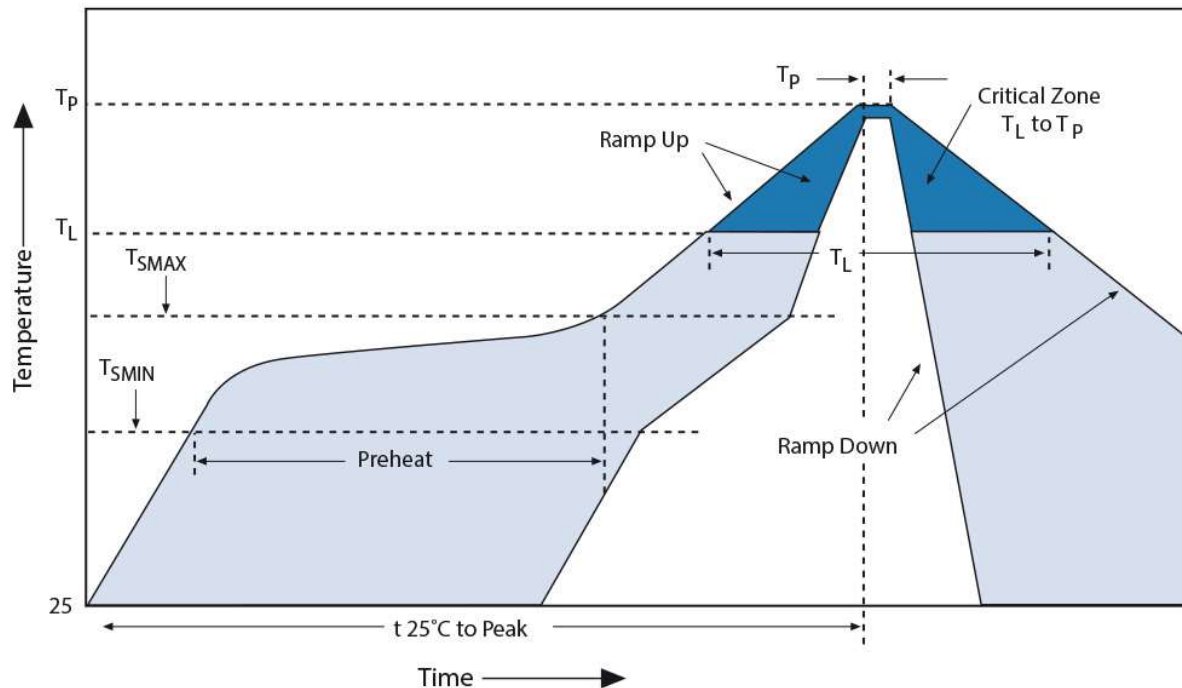
3) Recommended Stencil Pattern



4) Internal Circuit



5. Reflow Soldering Profile



[Classification Reflow Profiles]

| Profile Feature | Pb-free Assembly | Sn-Pb Eutectic Assembly |
|--|------------------|-------------------------|
| Average ramp-up rate (T_{Smax} to T_p) | 3°C/second max | 3°C/second max |
| Preheat | | |
| - Temperature Min (T_{Smin}) | 150 °C | 100 °C |
| - Temperature Max (T_{Smax}) | 200 °C | 150 °C |
| - Time (T_{Smin} to T_{Smax}) (ts) | 60-180 seconds | 60-120 seconds |
| Time maintain above: | | |
| - Temperature (T_L) | 217 °C | 183 °C |
| - Time (t_L) | 60-150 seconds | 60-150 seconds |
| Peak Temperature (T_p) | 260 °C | 235 °C |
| Time within 5°C of actual Peak Temperature (t_p) ² | 20-40 seconds | 10-30 seconds |
| Ramp-down Rate | 6 °C/second max | 6 °C/second max |
| Time 25°C to Peak Temperature | 8 minutes max. | 6 minutes max. |

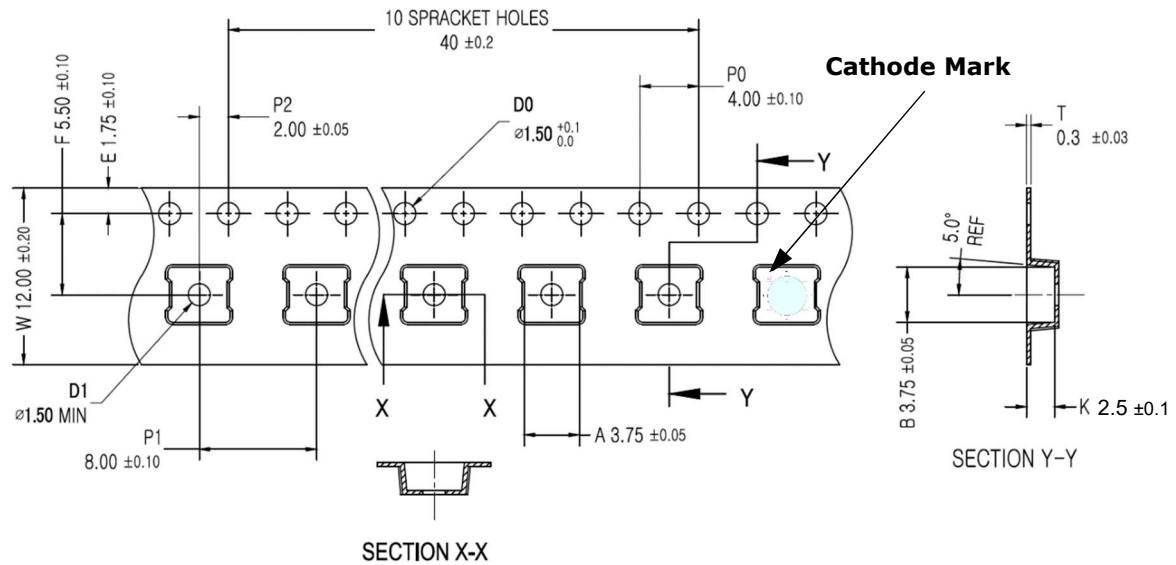
Notes

- All temperature refer to topside of the package, measured on the package body surface.
- The LED package is designed to be reflow soldered to a PCB. If dip soldered or hand soldered, PEC will not guarantee its reliability.
- Reflow soldering must not be done more than two times.
- When the LED PKG is cooled at the maximum temperature, a rapid temperature fall is not recommended.

6. Taping and Reel packing

1) Tape

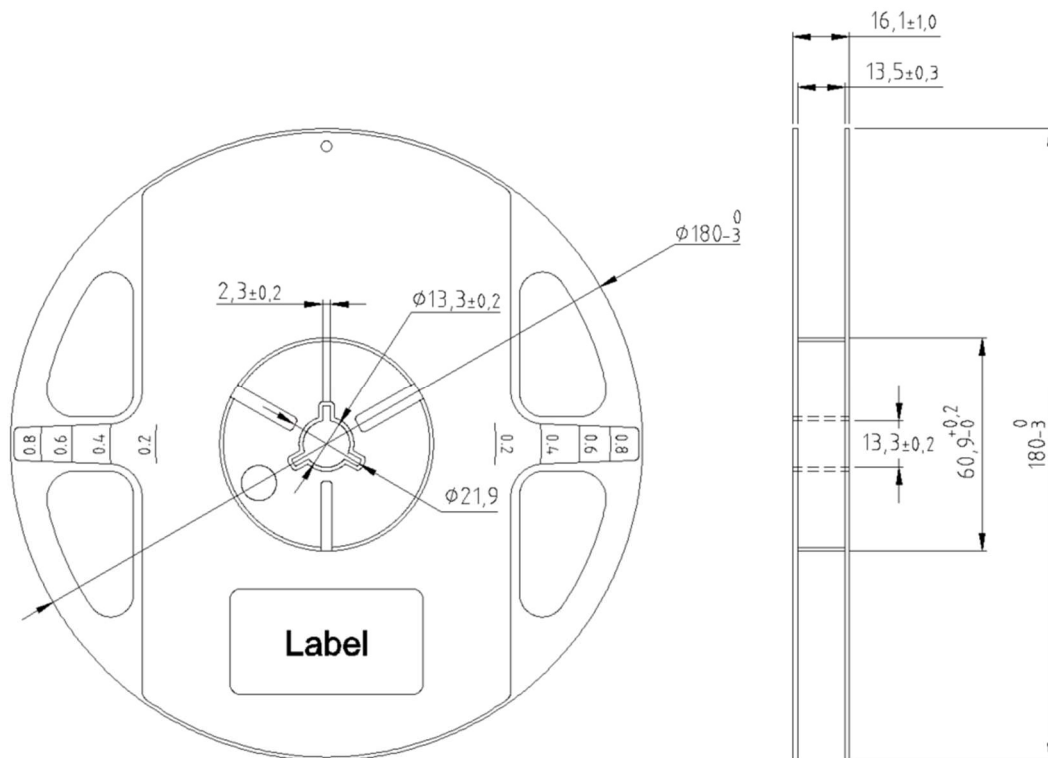
[Unit : mm]



2) Reel

- PKG Quantity : 1,000 PCS/Reel

[Unit : mm]



7. Precautions on use

1) Storage condition

- This LED PKG is vacuum-packed in an aluminum bag containing a dehumidifying agent. However, if the storage environment is not good, the LED PKG can absorb moisture.
- When soldering with LED PKG absorb moisture, vaporization of moisture may occur and internal air may expand. This may cause the quartz to peel off or deteriorate its optical properties.
- It is recommended to keep in the environment shown in the table below.

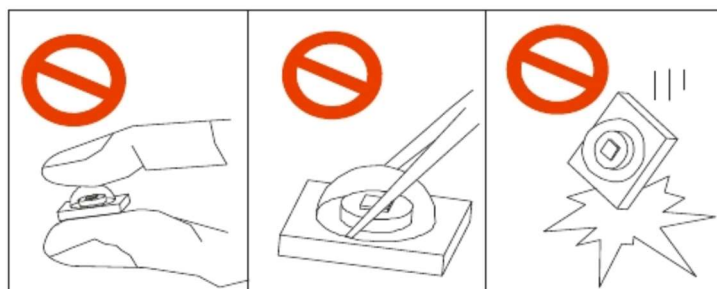
| Conditions | | Temperature | Humidity | Time |
|------------|-----------------------------|-------------|----------|--------------------------------------|
| Storage | Before Opening Aluminum Bag | 5°C ~ 30°C | < 50%RH | Within 1 Year from the Delivery Date |
| | After Opening Aluminum Bag | 5°C ~ 30°C | < 60%RH | ≤ 672 hours |
| Baking | | 65 ± 5°C | < 10%RH | 10 ~ 24 hours |

2) Circuit design

- When designing the circuit by applying the BR series, be sure to not exceed the absolute maximum ratings of each LED.
- For the BR series, it is designed to operate with forward voltage. If a reverse voltage is applied, the LED chip and the Zener diode can be damaged.
- For the current drive method, it is recommended to operate in the constant current mode.

3) Handling precautions

- When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristic.
- Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



- The silicon resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

4) ESD (Electrostatic Discharge)

- Use all objects and materials in the workplace for anti-static measures.
- Grounding
 - ① All instruments, JIG, and equipment in the workplace should be grounded and measured once a month by a ground resistance meter.
 - ② Workers should wear antistatic clothing and ground through a wrist strap or heel ground. Earth ring should be connected so as not to be shaken when grounding, and check for disconnection every day.
- The working surface of the work table is provided with a conductive mat and grounded. Periodically measure and check the conductivity state.
- The work table preferably has a surface resistance of 10^5 to 10^9 [Ω /SQ], and the metal work table is not good. (Breakage due to rapid discharge)
- Install conductive tiles or mats and regularly measure and manage grounding resistance and static electricity.
- Partially high static electricity is generated such as rotating body, TV, monitor, JIG. If it is non-conductive, use ionizer or anti-static spray regularly and prevent static electricity.
- In addition to general cases, use humidity control or partial humidifier to suppress the generation of static electricity.

5) Thermal Management

- Thermal management is closely related to the lifetime of LEDs.
- The temperature of the LED during operation must not exceed the junction temperature (T_j).
- For temperature management of the LED, the thermal resistance of the PCB and the spacing between the LEDs must be considered.
- For PCBs, a Cu based metal PCB is recommended, and if necessary, a heat sink should be attached to manage the LED temperature.

6) Eye Safety

- This UV LED PKG emits high power UV light.

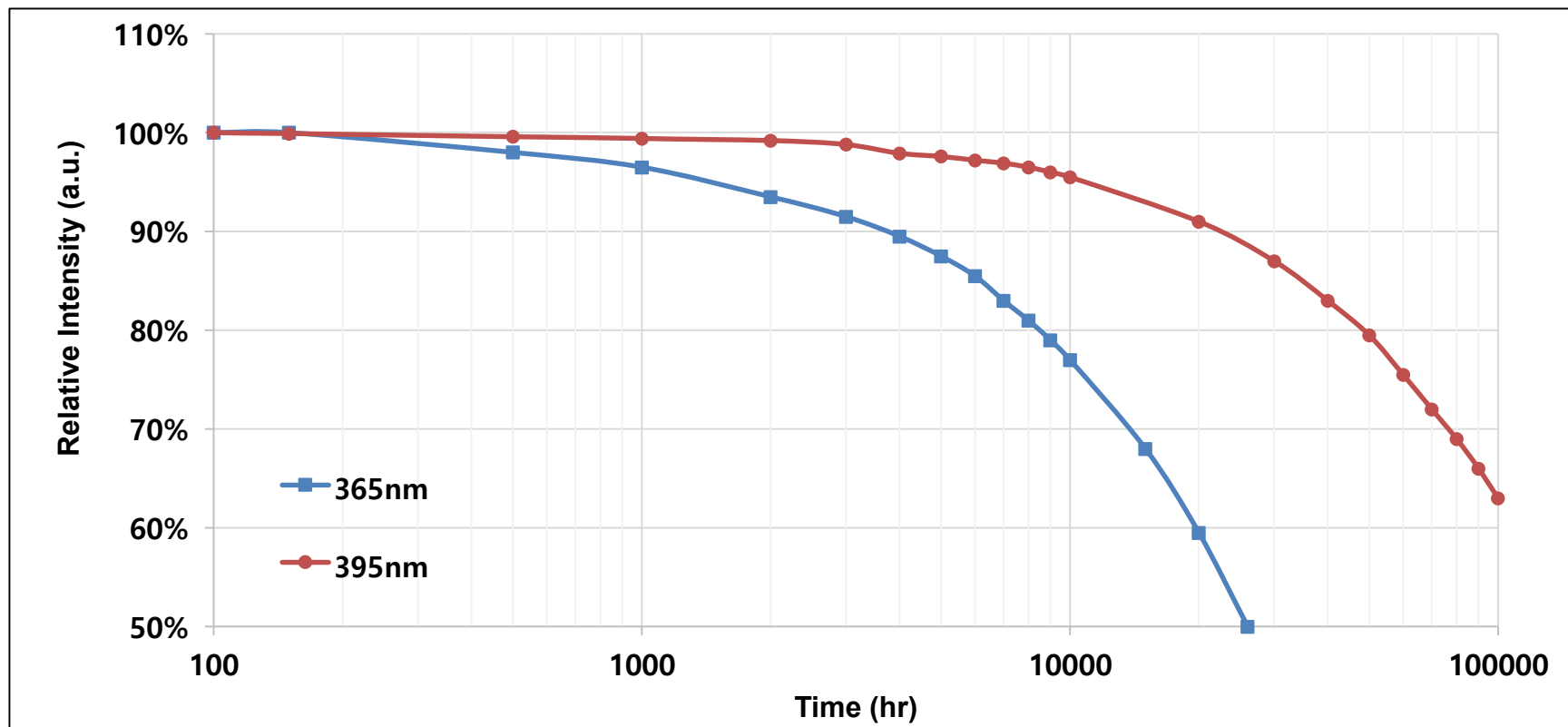
- Exposure to light with strong UV light can cause damage to the human eye and skin.
- Do not look directly or indirectly at UV light.
- If exposure to UV light is unavoidable, the body should be protected by suitable protection devices such as goggles and clothing.
- Attach the following warning labels on products/systems that use UV LEDs.





3535UVA PKG lifetime Extrapolation

BR35QVXXXL01X / BR35LVXXXL01X Series

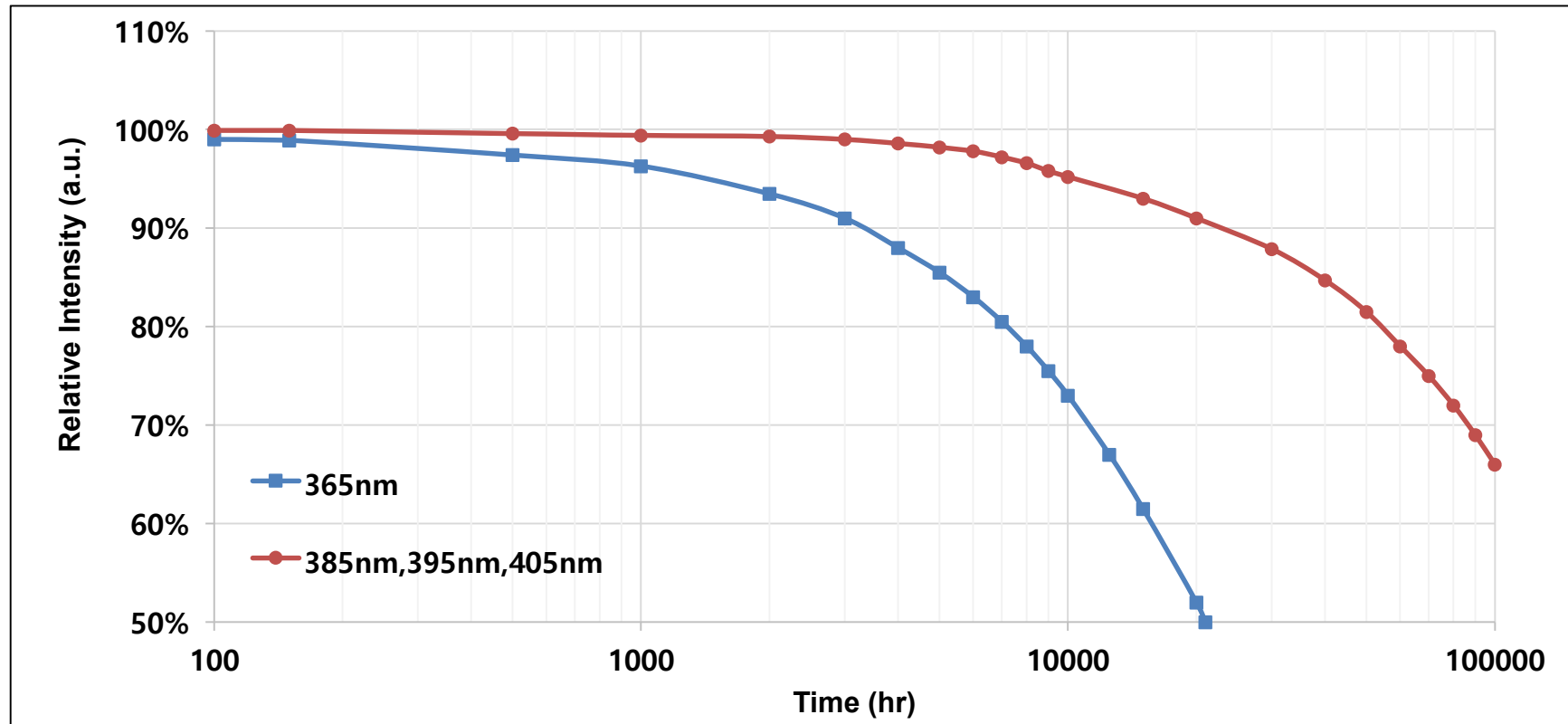


| No. | Wp(nm) | If(mA) | Ta(°C) | Tj(°C) | Calculated L70 | Calculated L80 |
|-----|---------------|--------|--------|--------|----------------|----------------|
| 1 | 365 | 500 | 50 | 75 | ~ 15,000 | ~ 9,000 |
| 2 | 385, 395, 405 | 500 | 50 | 71 | ~ 70,000 | ~ 40,000 |

* All characteristics shown are for reference only and are not guaranteed.

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AO35LLXXX01X / AO35LVXXX01X Series



| No. | Wp(nm) | If(mA) | Tj(°C) | Calculated L70 | Calculated L80 |
|-----|---------------|--------|--------|----------------|----------------|
| 1 | 365 | 350 | 60 | ~ 10,000 | ~ 7,000 |
| 2 | 385, 395, 405 | 350 | 60 | ~ 80,000 | ~ 50,000 |

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